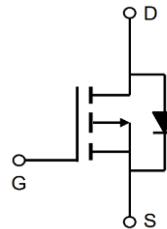


**-30V P-Channel Enhancement Mode MOSFET**
**Description**

The AP50P03D uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.


**General Features**

$V_{DS} = -30V$   $I_D = -50A$

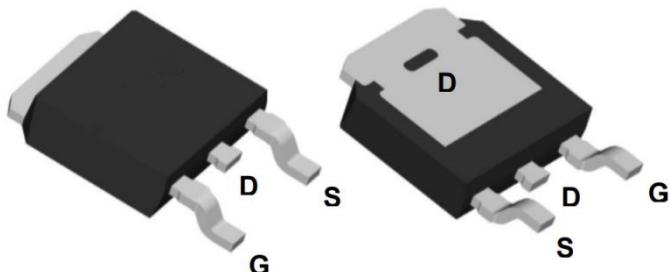
$R_{DS(ON)} < 16m\Omega$  @  $V_{GS} = -10V$  (**Type: 10.5m\Omega**)

**Application**

Lithium battery protection

Wireless impact

Mobile phone fast charging


**Package Marking and Ordering Information**

Product ID	Pack	Marking	Qty(PCS)
AP50P03D	TO-252-3L	AP50P03D XXX YYYY	5000

**Absolute Maximum Ratings (TC=25°C unless otherwise noted)**

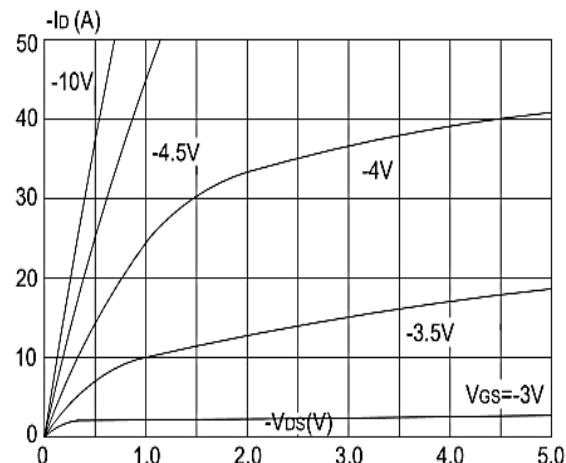
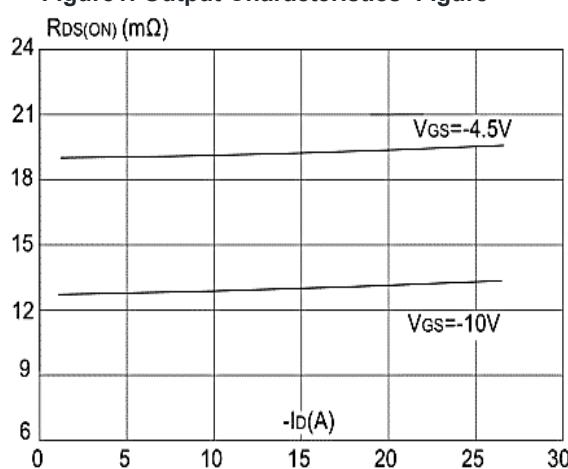
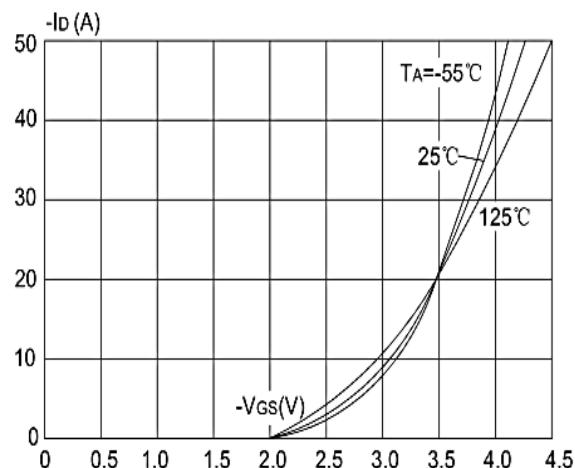
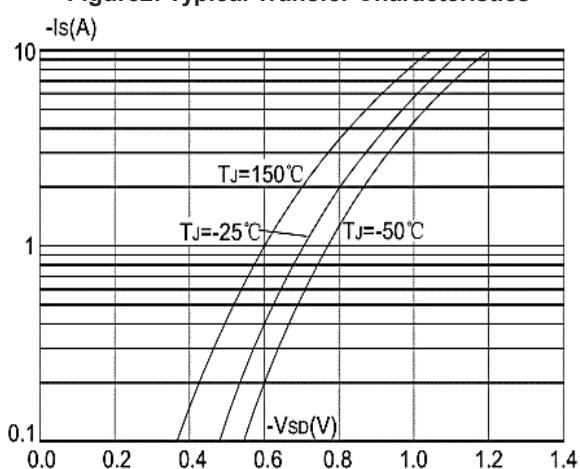
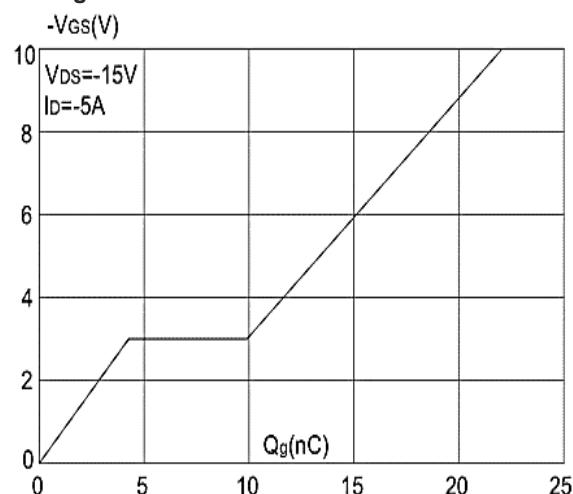
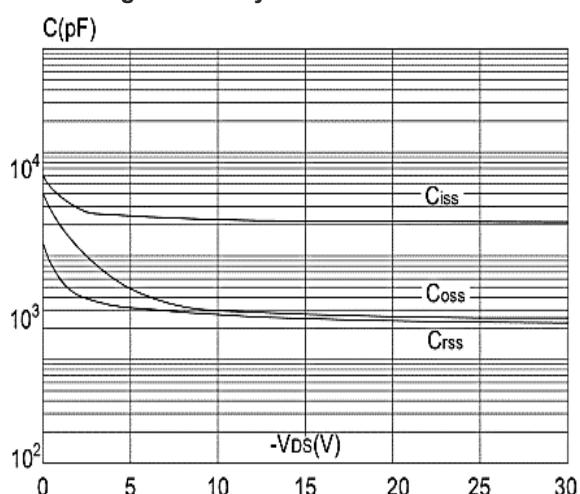
Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-30	V
V <sub>GS</sub>	Gate-Source Voltage	$\pm 20$	V
I <sub>D</sub> @T <sub>A</sub> =25°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-50	A
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ -10V <sup>1</sup>	-23	A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	-120	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	68	mJ
I <sub>AS</sub>	Avalanche Current	-29.4	A
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>4</sup>	310	W
T <sub>TSG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	62.5	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	24	°C/W

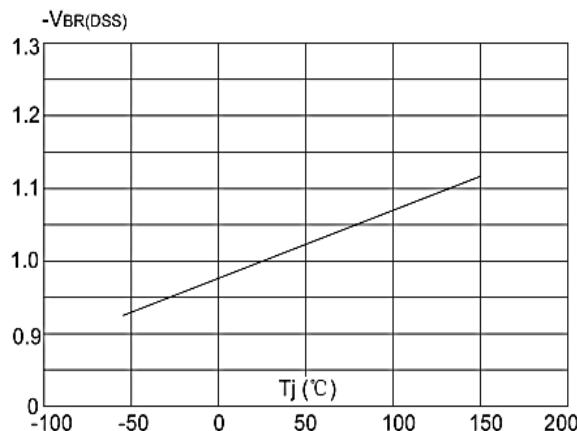
**-30V P-Channel Enhancement Mode MOSFET**
**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
V(BR)DSS	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$ , $I_D=-250\mu\text{A}$	-30	-32.5	-	V
IDSS	Zero Gate Voltage Drain Current	$V_{DS}=-30\text{V}$ , $V_{GS}=0\text{V}$ ,	-	-	-1	$\mu\text{A}$
IGSS	Gate to Body Leakage Current	$V_{DS}=0\text{V}$ , $V_{GS}=\pm 20\text{V}$	-	-	$\pm 100$	nA
VGS(th)	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=-250\mu\text{A}$	-1.2	-1.5	-2.5	V
RDS(on)	Static Drain-Source on-Resistance note3	$V_{GS}=-10\text{V}$ , $I_D=-10\text{A}$	-	10.5	16	$\text{m}\Omega$
		$V_{GS}=-4.5\text{V}$ , $I_D=-5\text{A}$	-	16	20	
Rg	Gate Resistance	$V_{DS}=0\text{V}$ , $V_{GS}=0\text{V}$ , $f=1\text{MHz}$	4.9	7.0	9.1	$\Omega$
Ciss	Input Capacitance	$V_{DS}=-24\text{V}$ , $V_{GS}=10\text{V}$ , $f=1.0\text{MHz}$	-	2130	-	pF
Coss	Output Capacitance		-	280	-	pF
Crss	Reverse Transfer Capacitance		-	252	-	pF
Qg	Total Gate Charge	$V_{DS}=-24\text{V}$ , $I_D=-1\text{A}$ , $V_{GS}=-10\text{V}$	-	22	-	nC
Qgs	Gate-Source Charge		-	4	-	nC
Qgd	Gate-Drain("Miller") Charge		-	5.8	-	nC
td(on)	Turn-on Delay Time	$V_{DD}=-24\text{V}$ , $I_D=-1\text{A}$ , $V_{GS}=-10\text{V}$ , $R_{GEN}=7.0\Omega$	-	9	-	ns
tr	Turn-on Rise Time		-	13	-	ns
td(off)	Turn-off Delay Time		-	48	-	ns
tf	Turn-off Fall Time		-	20	-	ns
IS	Maximum Continuous Drain to Source Diode Forward Current		-	-	-29.5	A
ISM	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-44	A
VSD	Drain to Source Diode Forward Voltage	$V_{GS}=0\text{V}$ , $I_S=-1\text{A}$	-	-0.74	-1.2	V

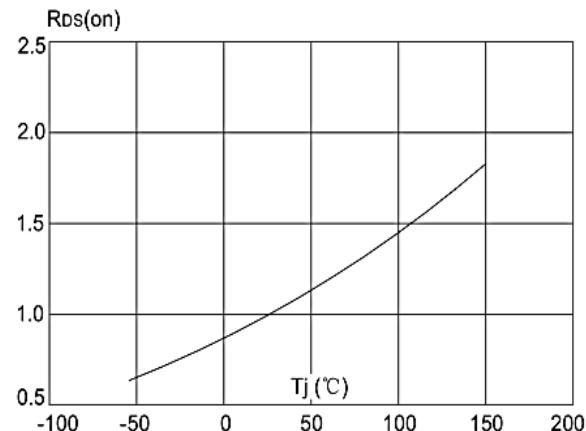
**Note :**

- 1、The data tested by surface mounted on a 1 inch 2 FR-4 board with 2OZ copper.
- 2、The data tested by pulsed , pulse width .The EAS data shows Max. rating .
- 3、The power dissipation is limited by  $175^\circ\text{C}$  junction temperature
- 4、EAS condition:  $T_J=25^\circ\text{C}$ ,  $V_{DD}=-24\text{V}$ ,  $V_G=-10\text{V}$ ,  $R_G=7\Omega$ ,  $L=0.1\text{mH}$ ,  $I_{AS}=-29.5\text{A}$
- 5、The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

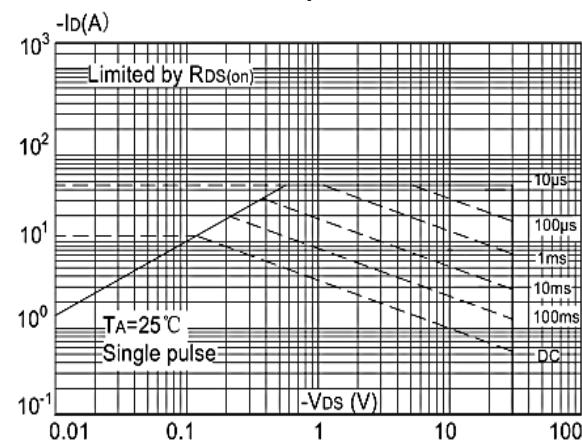
**-30V P-Channel Enhancement Mode MOSFET**
**Typical Characteristics**

**Figure 1: Output Characteristics**

**Figure 3: On-resistance vs. Drain Current**

**Figure 2: Typical Transfer Characteristics**

**Figure 4: Body Diode Characteristics**

**Figure 5: Gate Charge Characteristics**

**Figure 6: Capacitance Characteristics**

**-30V P-Channel Enhancement Mode MOSFET**


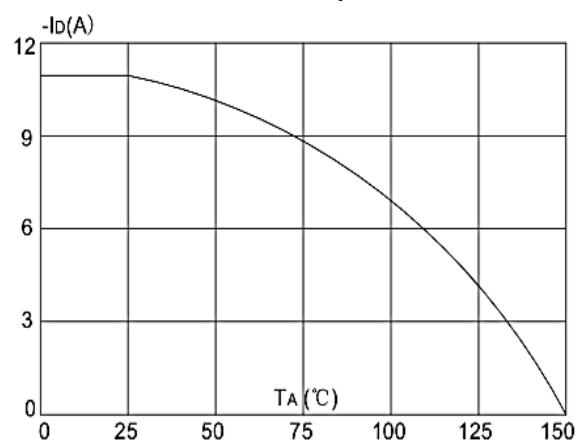
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**



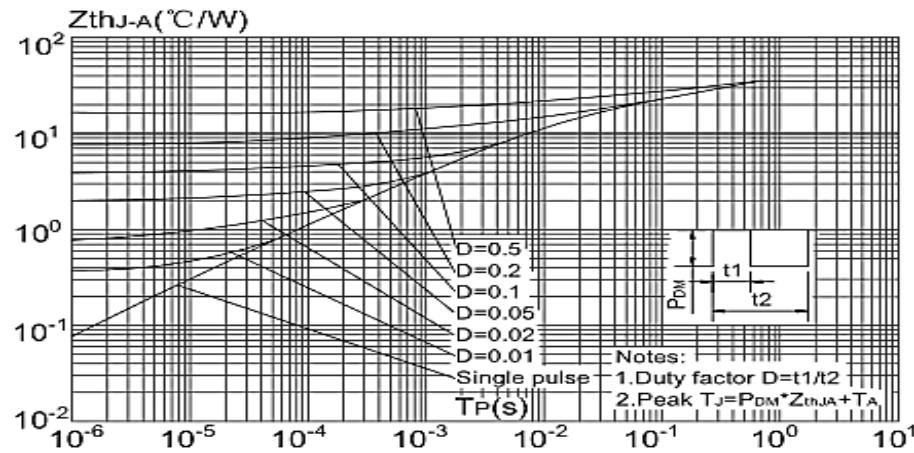
**Figure 8: Normalized on Resistance vs. Junction Temperature**



**Figure 9: Maximum Safe Operating Area**



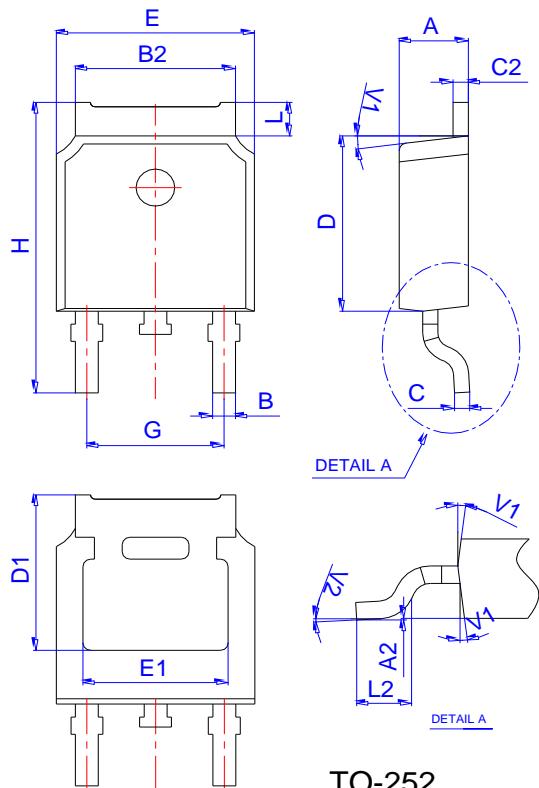
**Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature**



**Figure 11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**

**-30V P-Channel Enhancement Mode MOSFET**

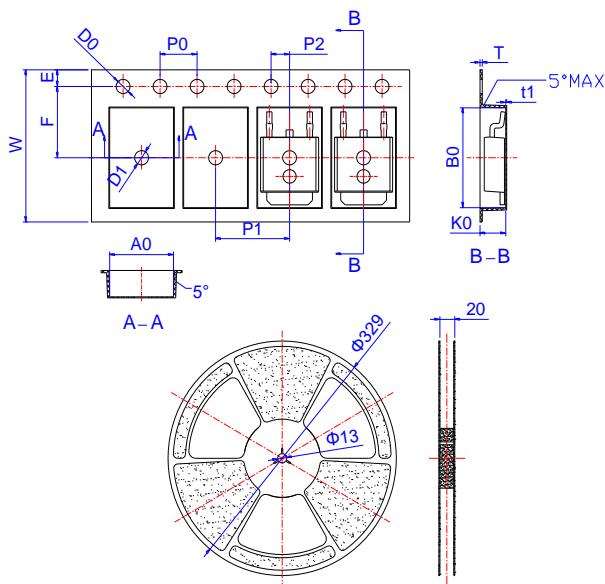
**Package Mechanical Data: TO-252-3L**



TO-252

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

**Reel Specification-TO-252**



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
W	15.90	16.00	16.10	0.626	0.630	0.634
E	1.65	1.75	1.85	0.065	0.069	0.073
F	7.40	7.50	7.60	0.291	0.295	0.299
D0	1.40	1.50	1.60	0.055	0.059	0.063
D1	1.40	1.50	1.60	0.055	0.059	0.063
P0	3.90	4.00	4.10	0.154	0.157	0.161
P1	7.90	8.00	8.10	0.311	0.315	0.319
P2	1.90	2.00	2.10	0.075	0.079	0.083
A0	6.85	6.90	7.00	0.270	0.271	0.276
B0	10.45	10.50	10.60	0.411	0.413	0.417
K0	2.68	2.78	2.88	0.105	0.109	0.113
T	0.24		0.27	0.009		0.011
t1	0.10			0.004		
10P0	39.80	40.00	40.20	1.567	1.575	1.583